

MATERIAL DECLARATION SHEET

BOURNS®

Material Number	2391-A			
Product Line	ADSL2/2 + ISOLATION DONGLE			
Compliance Date	November 2017			
RoHS Compliant	Yes	MSL		

Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
	bobin	0.35000	Phenolic Resin	9003-35-4	30	0.524046	1.7468
			cellulose microcrystalline	9004-34-6	30.00	0.524046	
			Calcium Stearate	1592-23-0	15.00	0.262023	
			Calcium carbonate	471-34-1	20.00	0.349364	
			low carbon steel	11121-90-7	4.00	0.069873	
			Copper	7440-50-8	0.50	0.008734	
			Tin	7440-31-5	0.50	0.008734	
	Plating	0.10000	Copper	7440-50-8	30.00	0.149727	0.4991
			Tin	7440-31-5	70.00	0.349364	
	Copper painting	0.20000	insulating layer	108-39-4	2.70	0.026951	0.9982
			Copper	7440-50-8	97.30	0.971232	
	Core	2.70000	Iron oxide	1309-37-1	70.00	9.432830	13.4755
			Manganese oxide	1317-35-7	22.00	2.964604	
			Zinc oxide	1314-13-2	8.00	1.078038	

MATERIAL DECLARATION SHEET



	Tape	0.20000	Polyethylene Terephthalate	25038-59-9	66.00	0.658801	0.9982
			n-Butyl Acrylate	141-32-3	22.00	0.219600	
			Zinc sulfate solution	7733-02-0	4.00	0.039927	
			Titanium dioxide	13463-67-7	1.60	0.015971	
			Melamine polyphosphate	20208-95-1	5.60	0.055898	
			Pigment	71832-85-4	0.80	0.007985	
	Flux	0.10000	Dimethylamine hydrochloride	506-59-2	100.00	0.499092	0.4991
	Ink	0.08000	acryl resin	9003-01-4	70.00	0.279491	0.3993
			Pigment	14302-13-7	30.00	0.119782	
RJ 11 connector	Housing	2.98507	polybutylene terephthalate resin	26062-94-2	85.00	12.663517	14.8983
			Antimony trioxide	1309-64-4	3.00	0.446948	
			Flame Retardant	68928-70-1/71342-77-3	5.00	0.744913	
			Glass Fiber	65997-17-3	5.00	0.744913	
			OTHER ADDITIVES	NA	2.00	0.297965	
	Insert	0.59701	polybutylene terephthalate resin	26062-94-2	85.00	2.532703	2.9797
			Antimony trioxide	1309-64-4	3.00	0.089390	
			Flame Retardant	68928-70-1/71342-77-3	5.00	0.148983	
			Glass Fiber	65997-17-3	5.00	0.148983	
			OTHER ADDITIVES	NA	2.00	0.059593	
	Contact pin	0.14925	Copper	7440-50-8	90.65	0.675263	0.7449
			Tin	7440-31-5	9.00	0.067042	

MATERIAL DECLARATION SHEET



			Phosphorus	7723-14-0	0.35	0.002607	
Capacitor	Dielectric	0.11579	Polyethylene Terephthalate	25038-59-9	99.97	0.577722	0.5779
			Antimony trioxide	1309-64-4	0.03	0.000173	
	Inner electrode	0.00066	Aluminum	7429-90-5	100.00	0.003283	0.0033
	Sprayed metal	0.07961	Zinc	7440-66-6	100.00	0.397303	0.3973
	Lead wire	0.09803	Iron	7439-89-6	72.50	0.354700	0.4892
			Copper	7440-50-8	21.50	0.105187	
			Tin	7440-31-5	6.00	0.029354	
	wax	0.03092	Polyethylene	9002-88-4	100.00	0.154324	0.1543
	Epoxy resin	0.17895	Epoxy resin	61788-97-4	94.00	0.839525	0.8931
			Brominated flame retardants	JAMP-SN0015	5.00	0.044656	
			Antimony trioxide	1309-64-4	1.00	0.008931	
	Acrylic resin	0.00001	2-Propenoic acid	53192-18-0	83.50	0.000058	0.0001
			Carbon black	1333-86-4	6.50	0.000004	
			Copper phthalocyaninato	147-14-8	10.00	0.000007	
PCB	FR4	2.25000	Glass fiber	65997-17-3	45.00	5.053302	11.2296
			Epoxy resin	26265-08-7	35.00	3.930346	
			Further additivie	Trade secret	5.00	0.561478	
			copper	7440-50-8	15.00	1.684434	
	Plating	0.01000	Tin	7440-31-5	100.00	0.049909	0.0499
TVS diode	Epoxy resin	0.00270	Silica fused	60676-86-0	87.70	0.011818	0.0135
			Epoxy resin	Trade secret	5.00	0.000674	
			Epoxy CN	29690-82-2	2.00	0.000270	
			Phenol resin	Trade secret	5.00	0.000674	

MATERIAL DECLARATION SHEET



			Carbon black	1333-86-4	0.30	0.000040	0.0105
	Copper alloy	0.00210	Copper	7440-50-8	94.56	0.009911	
			Iron	7439-89-6	2.23	0.000234	
			Zinc	7440-66-6	0.01	0.000001	
			Phosphorus	7723-14-0	0.03	0.000003	
			Silver	7440-22-4	3.17	0.000332	
	Silicon chip	0.00040	Silicon	7440-21-3	93.74	0.001871	0.0020
			Aluminum	7429-90-5	3.05	0.000061	
			Nickel	7440-02-0	3.08	0.000061	
			Gold	7440-57-5	0.13	0.000003	
	Silver epoxy	0.00008	Epoxy resin	Trade secret	2.99	0.000012	0.0004
			Functionalized ester	Trade secret	7.01	0.000028	
			Polymeric compound	Trade secret	2.99	0.000012	
Silver			7440-22-4	87.01	0.000347		
Gold bond wire	0.00004	Gold	7440-57-5	100.00	0.000200	0.0002	
Tin plating	0.00008	Tin	7440-31-5	100.00	0.000399	0.0004	
GDT	Tin plated Alloy 42	0.374	Iron	7439-89-6	56.4	1.052764	1.8666
			Nickel	7440-02-0	40.8	0.761574	
			Tin	7440-31-5	2.8	0.052265	
	Ceramic	0.107	Aluminum oxide	1344-28-1	93.19	0.497661	0.5340
			Silicon dioxide	7631-86-9	4.9	0.026167	
	Metallization		Tungsten	7440-33-7	1.49	0.007957	
			Nickel	7440-02-0	0.42	0.002243	
	Cusil™	0.003	Silver	7440-22-4	72	0.010780	0.0150
			Copper	7440-50-8	28	0.004192	
	Gas	0.0007	Argon	7440-37-1	100	0.003494	0.0035
Blue Ink	0.001	Ink (Proprietary mixture)	N/A	100	0.004991	0.0050	

MATERIAL DECLARATION SHEET



	Tin plated Copper	0.15	Copper	7440-50-8	97	0.726178	0.7486
			Tin	7440-31-5	3	0.022459	
Housing	Carbotex material	8.67000	Plycarbonate	25971-63-5	99.30	42.968338	43.2712
			Anti-oxidant	Trade secret	0.50	0.216356	
			Flame Retardant	Trade secret	0.20	0.086542	
solder wire	SAC387	0.10000	Tin	7440-31-5	95.50	0.476632	0.4991
			Silver	7440-22-4	3.80	0.018965	
			Copper	7440-50-8	0.70	0.003494	
Anti-corrosion & Connector gel	Dielectric Gel	0.40000	Polyalphaolefin	68037-01-4	88.25	1.761793	1.9964
			Fumed Silica	68611-44-9	5.00	0.099818	
			C11-14 Branched Alyklamines	80939-62-4	4.00	0.079855	
			Antioxidant	41484-35-9	2.00	0.039927	
			Barium Petroleum Sulfonate	61790-48-5	0.25	0.004991	
			Unamine O	27136-73-8	0.50	0.009982	
	Total	20.03640					

This Document was updated on: November 2017

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.